

L Number	Hits	Search Text	DB	Time stamp
1	9	wafer with encapsulat\$3 with dic\$3 with scrib\$3	USPAT; US-PGPUB	2003/06/28 14:27
2	289	wafer with encapsulat\$3 with (dic\$3 or scrib\$3)	USPAT; US-PGPUB	2003/06/28 14:32
3	1	("6403449").PN.	USPAT; US-PGPUB	2003/06/28 14:34
4	55187	warp\$3	USPAT; US-PGPUB	2003/06/28 14:34
5	501984	resin or encapsulat\$3	USPAT; US-PGPUB	2003/06/28 14:34
6	2568	warp\$3 with (resin or encapsulat\$3)	USPAT; US-PGPUB	2003/06/28 14:35
7	58469	dic\$3	USPAT; US-PGPUB	2003/06/28 14:35
8	178	(warp\$3 with (resin or encapsulat\$3)) and dic\$3	USPAT; US-PGPUB	2003/06/28 14:35
9	267	(resin or encapsulat\$3) with via with solder	USPAT; US-PGPUB	2003/06/28 15:29
10	418111	@ad>20010200 @rlad>20010200	USPAT; US-PGPUB	2003/06/28 15:30
11	148	((resin or encapsulat\$3) with via with solder) not (@ad>20010200 @rlad>20010200) 438/\$.ccls.	USPAT; US-PGPUB	2003/06/28 15:30
-	65379		USPAT; US-PGPUB	2003/06/01 18:14
-	463378	semiconductor or ic or "integrated circuit" or microelectronic	USPAT; US-PGPUB	2003/05/29 17:11

U.S. Patent

Sep. 29, 1899

Sheet 3 of 12

5,960,260

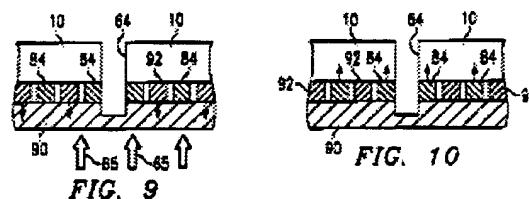
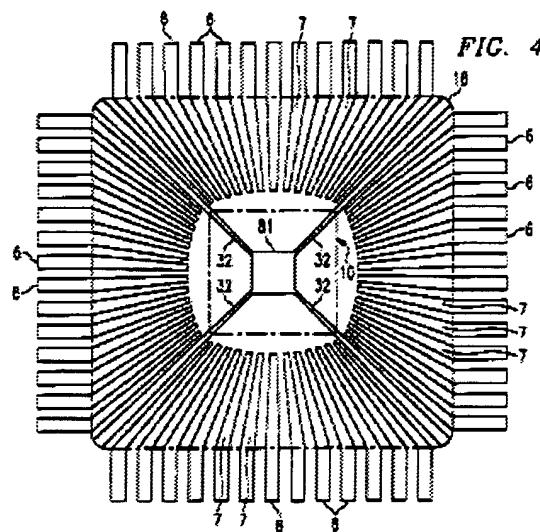


FIG. 9

US-PAT-NO: 6188127

DOCUMENT-IDENTIFIER: US 6188127 B1

TITLE: Semiconductor packing stack module and method of producing the same

----- KWIC -----

Moreover, in accordance with the present invention, in a semiconductor package stack module, a multicarrier body formed with a plurality of carriers not separated from each other is subjected to mounting of LSI chips, connection of the LSI chips and carriers via bumps, sealing with resin, thinning, burn-in tests, multistage connection, and electric characteristic tests, and then the plurality of carriers are separated from each other by one of laser, scribing, dicing, and choco-braking.